

PATENT APPLICATION SERIAL NO. \_\_\_\_\_

U.S. DEPARTMENT OF COMMERCE  
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FEE RECORD SHEET

07/29/2002 EFSPROD 00000006 10064575

01 FC:101	740.00 OP
02 FC:581	40.00 OP

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10/064575  
07/29/02

Stylesheet Version: 1.0

*Patent fees are subject to annual revisions on or about October 1st of each year.*

**TOTAL FEES AUTHORIZED: \$ 780**

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Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 13	103	\$ 18	0	\$ 0
Independent Claims: 2	102	\$ 84	0	\$ 0

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Page 1 of 1

# TRANSMITTAL FORM



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Submission Type: Utility Patent  
Filing

Attorney Docket  
Number:

7808-US-  
PA

## BUMP LAYOUT ON SILICON CHIP

First Named Inventor: Mr. Wen-Chih Yang

### SUBMITTED BY

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### Attached Files:

declaration	7808declaration1.tif
declaration	7808declaration2.tif
specification	7808usf.xml
patent-assignments	7808usasgn.xml
fee-transmittal	7808usfee.xml

Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 16725  
Application ID: 10064575  
Title of Invention: BUMP LAYOUT ON SILICON CHIP  
First Named Inventor: Wen-Chih Yang  
Domestic/Foreign Application: Domestic Application  
Filing Date: null  
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Confirmation Number: 0  
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Attached Image File(s):

7808declaration1.tif

7808declaration2.tif

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